FEATURES

- * HIGH DENSITY SOCKETS FOR IC WITH A PITCH OF 1.778 MM
- * LOW PROFILE DESIGN.
- * SAVING ON PCB REAL SETATE.
- * MANUALLY AND AUTOMATICALLY INSERTABLE.
- * CLOCSED BOTTOM DESIGN TO PREVENT SOLDER WICKING.
- * PROVIDED NEW TYPE FOR FLUX PROTECTION.

TECHNICAL DATA **MATERIAL**

- * CONTACT:PHOSPHOR BRONZE.
- * PLATING:TIN PLATED.
- * INSULATOR:GLASS FILLED POLYESTER P.B.T. (UL-94 V-0)

MACHANICAL

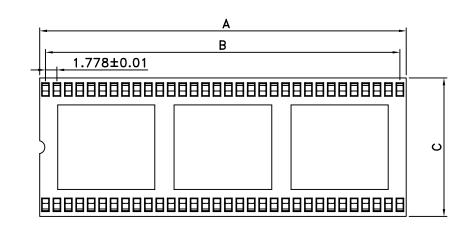
- * OPERATING TEMPERATURES:-55°C~+125°C.
- * INSERTION FORCE: 450 G * WITHDRAWAL FORCE: 70 G MIN

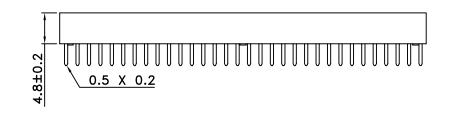
ELECTRICAL

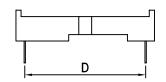
- * CURRECT RATING: 1 AMP. MAX.
- * CONTACT RESISTANCE: 20M OMH MIN.
- * WITHSTANDING VOLTAGE: AC 600V/MINUTE.

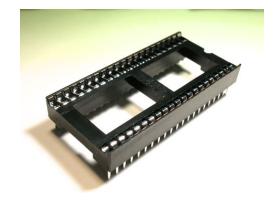
TOLERANCES ARE

X XX .XXX









POSITION	Α	В	С	D	SPACE
40		33.78			
42	37.34	35.56	17.70	15.24	
48	42.67	40.89	17.70	15.24	
52	46.23	44.45	17.70	15.24	06
54	48.01	46.23	17.70	15.24	
56		48.01			
64	56.90	55.12	17.70	15.24	

DESCRIPTION: HIGH DESITY 1.778MM IC SOCKET